

ABSTRACT OF THE DISCLOSURE

First, a board is placed on a board mounting portion with a lower mold and an upper mold being opened. Then, a resin material having such size and shape that correspond to the size and shape of a cavity
5 formed in the lower mold is fitted in the cavity. Thereafter, the resin material is heated resulting in melted resin. Thereafter, the lower mold and the upper mold are closed, with a space formed by the upper mold and the lower mold being reduced in pressure. As a result, chips and wires are
10 immersed in the melted resin. Thereafter, the melted resin is set, so that a resin mold product including the board and the set resin is formed.